

Title (en)

Free-cutting copper alloys

Title (de)

Automatenlegierung auf Kupferbasis.

Title (fr)

Alliage de décolletage à base de cuivre.

Publication

EP 1508626 A1 20050223 (EN)

Application

EP 04077561 A 19981116

Priority

- EP 98953070 A 19981116
- JP 28792198 A 19981009

Abstract (en)

Free-cutting alloys with industrially satisfactory machinability comprising 69 to 79 percent, by weight, of copper, 2.0 to 4.0 percent, by weight, of silicon; 0.02 to 0.4, by weight, of lead and the remaining percent, by weight, of zinc. <IMAGE>

IPC 1-7

C22C 9/04; **C22F 1/08**

IPC 8 full level

C22F 1/00 (2006.01); **C22C 9/04** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP KR)

C22C 9/04 (2013.01 - EP KR); **C22F 1/08** (2013.01 - EP)

Citation (search report)

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Designated contracting state (EPC)

BE DE FI FR GB IT SE

DOCDB simple family (publication)

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